MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

RB160VAM-40TR

Product specification





FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Low power loss,high efficiency.
- For use in low voltage high frequency inverters, free wheeling, and polarity protection applications.
- Guardring for over voltage protection.
- High temperature soldering guaranteed:260°C/10 seconds at terminals

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking		
SOD-323HE	1	14S		



MAXIMUM RATINGS(Ta = 25℃)

Parameter	Symbol	Limits	Unit	
Maximum repetitive peak reverse voltage	VRRM	40	V	
Maximum RMS voltage	VRMS	28	V	
Maximum DC blocking voltage	VDC	40	V	
Maximum average forward rectified current at TC =75 $^\circ\!\!\!\mathrm{C}$	IF(AV)	1	А	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	15	A	
	RθJA	210		
Typical thermal resistance (Note 1)	RθJL	70	℃/ W	
Operating junction temperature range	TJ	-55 ~ +150	°C	
storage temperature range	TSTG	-55 ~ +150	°C	

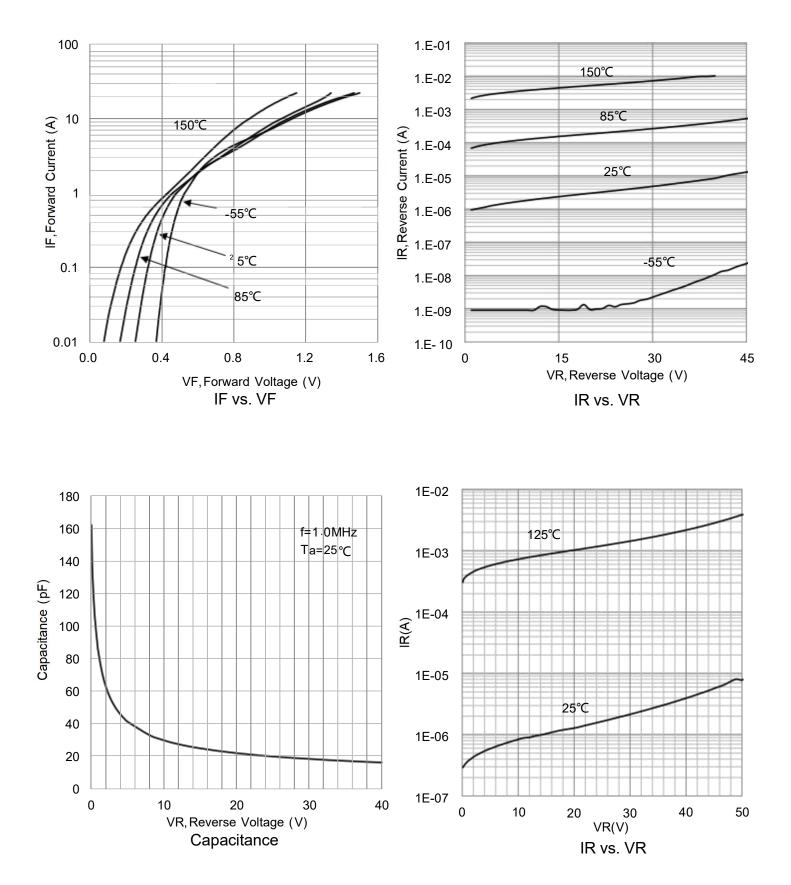
Note: 1.8.0mm²(.013mmthick) landareas

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min	Тур	Max	Unit
Maximum instantaneous forward (IF =0.7 A, TJ = 25 ℃)	VF	_	_	0.46	V
(IF = 1.0 A, TJ = 25 ℃)		_	-	0.6	
Maximum DC reverse current at rated					
DC blocking voltage TA = 25 $^\circ C$	IR	_	5	50	uA
TJ = 125 ℃		-	2.5	60	mA
Typical junction capacitance at 4 . 0V, 1MHz	CJ	-	50	-	pF

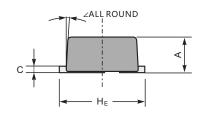


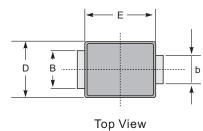
ELECTRICAL CHARACTERISTICS CURVES

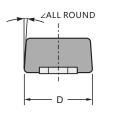


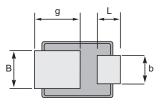


OUTLINE AND DIMENSIONS







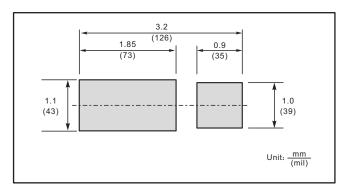


Bottom View

UNIT		А	b	В	С	D	E	H _E	g	L	2
mm –	max	0.77	0.75	0.95	0.20	1.45	2.3	2.7	1.55	0.8	
	min	0.57	0.45	0.65	0.10	1.25	2.1	2.3	1.1	0.4	100
mil	max	30	30	37	8	57	91	106	61	31	12°
	min	22	18	26	4	49	83	91	43	16	

SOLDERING FOOTPRINT

RECOMMENDED PAD



REEL SPECIFICATION

P/N	PKG	QTY
RB160VAM-40TR	SOD-323HE	3000



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